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**(54) BONDING PAD  
STRUCTURE FOR  
SEMICONDUCTOR DEVICE**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To prevent peeling or cracking of an applied insulating film which constitutes an interlayer insulating film in a bonding pad structure for a semiconductor device.

**SOLUTION:** A pad layer 14b, an interlayer insulating film 16, a pad layer 20b, an interlayer insulating film 22, a pad layer 26b, and an interlayer insulating film 28 are successively formed on an insulating film 12 for covering the surface of a semiconductor substrate 10 into a laminated state. Both insulating films 16 and 22 contain applied insulating films, such as SOG(spin-on-glass), etc., and the upper surfaces of the films 16 and 22 are flattened through CMP (chemical mechanical polishing), etc. Plural of connection

*managing*

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